SUNBONDER® ULTRASONIC SOLDERING SYSTEM

Ultrasonic soldering makes it possible to solder glass, ceramics and low-solderability metals, such as Al, Mo, stainless steel etc.

Common Specification

[GENERATOR]

Ultrasonic-power Temperature range $1\sim12W$ (0.1W interval) OFF, 200°C~ (10°C interval)

Display Frequency, US Power, Temperature, Amplitude

External monitoring Temperature, US Power (0-10V)

Power Requirements AC100V/240V, 50/60Hz [IRON]

Transducer Tip material

Heater

PZT Langevin type Stainless steel

High performance sheathed heater

****CUSTOMIZED TIP SHAPE AVAILABLE**

USM-5 series

line-up

Detail Specification









8	A.C.	USM-560	USM-540	USM-528
Ultrasonic frequency		60kHz	40kHz	28kHz
Ultrasonic power(max)		12W	20W*	70W *
Generator	SIZE	210 x 235 x 90		260 x 320 x 140
	Weight	5kg		10kg
Heater	max temp.	500°C	600°C	350℃
	Power	65W	150W	200W
IRON	Tip SIZE	Φ1.0~4.0mm	Ф10.0mm	50mm x 10mm
	Weight	210g	520g	1,500g
	Hand Switch	No		Yes
	Cooling	No		FAN
Replaced models		USM-III / USM-IV	SO-6	USM-28
Applications		Electronic componets PV wire bonding(point) OLED	Electronic device PV wire bonding(line) Al terminal soldering	Target material bonding

^{*} adjustable range on display is 1-12W only

We offer manual ultrasonic irons, dipping ultrasonic soldering pot, jet type ultrasonic soldering machine and various automated soldering solutions.

Please feel free to get in touch with us.

Sanwa Components International

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<u>Ultrasonic Soldering System</u>

SUNBONDER® USM-5

SUNBONDER is an ultrasonic soldering device that produces high quality soldered joints. The soldering iron consists of a high performance sheath heater and transducer, supplying heat and ultrasonic oscillations to the tip. Using CERASOLZER, a solder alloy specially formulated for use with the SUNBONDER, you can easily solder directly to glass, ceramics and other low solderability

materials, such as Al, Mo, or stainless steel.

Ultrasonic soldering mechanism

Standard soldering joins metals by eliminating oxide surface, using flux, and bonds substrates by accelerating the wetting of a metal and a solder.

SUNBONDER facilitates that process using, ultrasonic energy.

High performance soldering is implemented by the cavitation effect which breaks the oxide surface and eliminates bubbles in solder.

You can easily solder directly to glass, ceramics and other low solderability materials by the application of this law.

Soldering to glass, ceramics and low solderability metals

CERASOLZER is used for soldering to glass, ceramic and low solderability metals. CERASOLZER is a special solder alloy with high oxgen affinity metal.

A strong chemical bond of Zinc and Oxygen is achieved between the substrate and CERASOLZER by applying ultrasonic oscillation with the SUNBONDER device to the melting CERASOLZER solder alloy.

This superior bonding technique provides an excellent airtight, weatherproof, humidity resistant seal as well as joints with good electro-conductivity between interconnected layers.

SUNBONDER features

[Special soldering]

Direct soldering to glass, ceramics, low solderability metals without Flux.

[Performance]

Stable ultrasonic frequency and temperature with new feeback system.

[Oscillation]

Adjustable ultrasonic-power output.

[Temperature]

Heater temperature is posible to adjust at intervals of 10° C. [Display]

Frequency, power, heater temperature and amplitude

Accessories

Foot Switch	1	
Soldering iron stand	1	
Power source cord	1	
Spanner for changing tip	2	
Fuse	2	

OPTION

Custom tip

External Control (Analog 0-10V)

PC control (LAN)



For operating the device, refer to the instruction manuals. Don't use near water, under conditions of high humidity, dust and soot filled places,

to avoid electric shock, fire or breakdown.

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